

35.2mm (1.38 INCH) 5x8 SINGLE COLOR DOT MATRIX DISPLAY

Part Number: TA16-11SURKWA Hyper Red

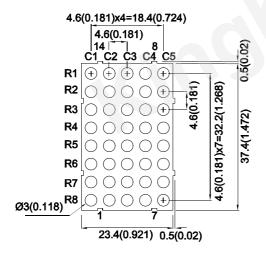
Features

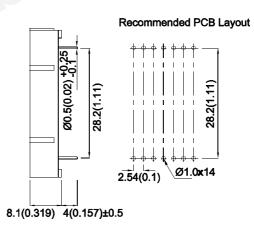
- 1.38 inch matrix height.
- Dot size 3mm.
- Low current operation.
- High contrast and light output.
- Stackable horizontally and vertically.
- Column cathode and column anode available.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- Standard : gray face, white dot.
- RoHS compliant.

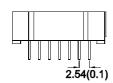
Description

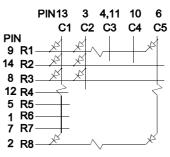
The Hyper Red source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram













Notes

- 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
- 2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAE0084 REV NO: V.8A DATE: JUN/28/2016 PAGE: 1 OF 6
APPROVED: Wynec CHECKED: Joe Lee DRAWN: F.Zhang ERP: 1332000127

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (ucd) [1] @ 10mA		Description
			Min.	Тур.	•
TA16-11SURKWA	Hyper Red (AlGaInP)	White Diffused	52000	130000	Column Anode
			*21000	*36000	

Note:

- 1. Luminous intensity/ luminous Flux: +/-15%.

 * Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	645		nm	IF=10mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=10mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=10mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.85	2.5	V	IF=10mA
lr	Reverse Current	Hyper Red		10	uA	V _R =5V

Notes:

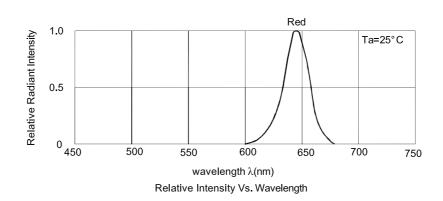
- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Values	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating / Storage Temperature	-40°C To +85°C			
Lead Solder Temperature[2]	260°C For 3-5 Seconds			

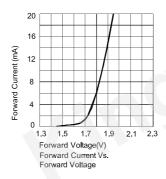
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

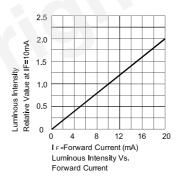
SPEC NO: DSAE0084 **REV NO: V.8A** DATE: JUN/28/2016 PAGE: 2 OF 6 APPROVED: Wynec **CHECKED:** Joe Lee DRAWN: F.Zhang ERP: 1332000127

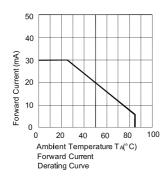


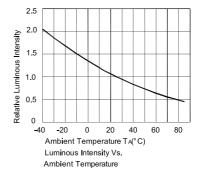
Hyper Red

TA16-11SURKWA



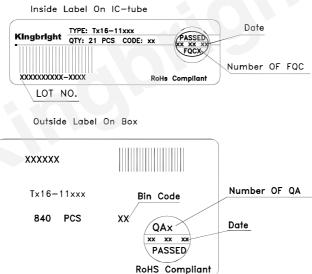






SPEC NO: DSAE0084 APPROVED: Wynec REV NO: V.8A CHECKED: Joe Lee DATE: JUN/28/2016 DRAWN: F.Zhang PAGE: 3 OF 6 ERP: 1332000127

PACKING & LABEL SPECIFICATIONS TA16-11SURKWA INSIDE LABEL 21PCS/TUBE OUTSIDE LABEL 40TUBE/10#BOX



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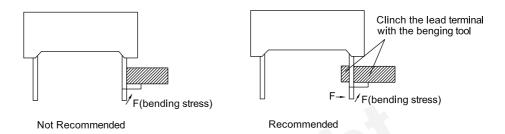
SPEC NO: DSAE0084 REV NO: V.8A DATE: JUN/28/2016 PAGE: 4 OF 6
APPROVED: Wynec CHECKED: Joe Lee DRAWN: F.Zhang ERP: 1332000127

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

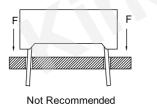
Do not bend the component leads by hand without proper tools.

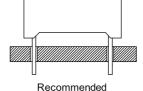
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



Installation

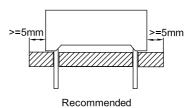
- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.





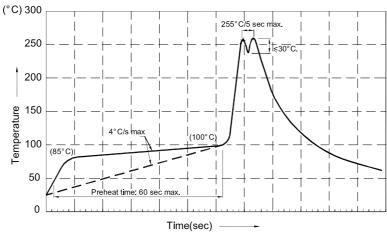
3.The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.





SPEC NO: DSAE0084 REV NO: V.8A DATE: JUN/28/2016 PAGE: 5 OF 6
APPROVED: Wynec CHECKED: Joe Lee DRAWN: F.Zhang ERP: 1332000127

Recommended Wave Soldering Profiles:



Notes:

- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.
- 7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Soldering General Notes:

- 1. Through-hole displays are incompatible with reflow soldering.
- 2.If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

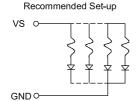
CLEANING

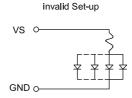
- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2.If cleaning is required, Kingbright recommends to wash components with water only.

 Do not use harsh organic solvents for cleaning because they may damage the plastic parts.
- 3.The cleaning process should take place at room temperature and the devices should not be washed for more than one minute.
- 4. When water is used in the cleaning process, immediately remove excess moisture from the component with forced-air drying afterwards.

CIRCUIT DESIGN NOTES

- 1.Protective current-limiting resistors may be necessary to operate the LEDs within the specified range.
- 2.LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.





- 3. The driving circuit should be designed to protect the LED against reverse voltages and transient voltage spikes when the circuit is powered up or shut down.
- The safe operating current should be chosen after considering the maximum ambient temperature of the operating environment.
- 5. Prolonged reverse bias should be avoided, as it could cause metal migration, leading to an increase in leakage current or causing a short circuit.

SPEC NO: DSAE0084 REV NO: V.8A DATE: JUN/28/2016 PAGE: 6 OF 6
APPROVED: Wynec CHECKED: Joe Lee DRAWN: F.Zhang ERP: 1332000127